(relative to the discharge in Ah/m^2) compared with active layers in base-metal electroplating. This is predominantly ascribed to the attack on this active layer by additives which dissolve the platinum metals of the layer by complexing. Additionally, cyanate and carbonate formation can also be disruptive in certain types of baths.

To solve this problem attempts have been made hitherto to keep organic compounds away from the anode. This occurred through the use of a membrane which in the case of a cation or anion exchange membrane, keeps charged additives away completely or, in the case of a diffusion membrane, greatly reduces the flow of additives to the anode. However, this solution requires a closed case with an anolyte around the anode, a separation of the electrolyte, and a higher voltage. Thus, it can be used only at the cost of further disadvantages. Also, this process cannot be used at all in cases in which e.g. form anodes are used, such as e.g. for the internal coating of tubes.

Therefore it is the object of the invention to provide anodes which lead to a clearly reduced additive degradation and at the same time avoid the disadvantages of the use of a membrane.

This object is surprisingly achieved by the anode according to claims 1 to 11. The invention also relates to the electroplating process according to claim 12 and the use of the anode according to claim 13. The invention further relates to an anode according to claims 14 to 17, an electroplating process according to claim 18 and the use of the anode according to claim 19.

BDR 4/13/11

The anode according to the invention for electroplating is distinguished by having an anode base and a shield, the anode base having a support material and an active layer, wherein the shield is attached to the anode base at a distance from it and is reducing the transport of material to and from the anode base.